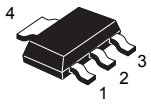
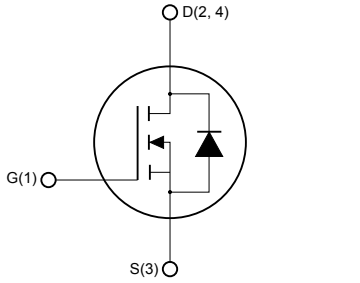
Automotive-grade N-channel 60 V, 0.07 Ω typ., 4 A STripFET II Power MOSFET in a SOT-223 package



SOT-223



Int_schem_nTnZ_SOT_223

Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STN4NF06L	60 V	< 0.1 Ω	4 A

- AEC-Q101 qualified
- Exceptional dv/dt capability
- 100% avalanche tested
- Low gate charge

Applications

- Switching applications

Description

This Power MOSFET has been developed using STMicroelectronics' unique STripFET process, which is specifically designed to minimize input capacitance and gate charge. This renders the device suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.

Product status link
STN4NF06L

Product summary	
Order code	STN4NF06L
Marking	4NF06L
Package	SOT-223
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V_{GS} = 0 V)	60	V
V_{GS}	Gate-source voltage	±16	V
I_D(1)	Drain current (continuous) at T_C = 25 °C	4	A
	Drain current (continuous) at T_C = 100 °C	2.9	A
I_{DM}(2)	Drain current (pulsed)	16	A
P_{TOT}	Total power dissipation at T_C = 25 °C	3.3	W
	Derating Factor	0.026	W/°C
dv/dt(3)	Peak diode recovery avalanche energy	10	V/ns
E_{AS}(4)	Single pulse avalanche energy	200	mJ
T_{stg}	Storage temperature range	-55 to 150	°C
T_J	Operating junction temperature range		

1. *Current limited by the package.*
2. *Pulse width limited by safe operating area.*
3. *I_{SD} ≤ 3 A, di/dt ≤ 150 A/µs, V_{DD} = $V_{(BR)DSS}$, T_J ≤ T_J max.*
4. *Starting T_J = 25 °C, I_D = 4 A, V_{DD} = 30 V.*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj\text{-}pcb}$ (1)	Thermal resistance junction-pcb	38	°C/W
$R_{thj\text{-}pcb}$(2)		100	°C/W
T_J(3)	Maximum lead temperature for soldering purpose	260	°C

1. *When Mounted on FR-4 board with 1 inch2 pad, 2 oz. of Cu. and t <10 s.*
2. *When mounted on minimum recommended footprint.*
3. *For 10 s 1.6 mm from case.*

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 3. On-/off-states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 250 µA	60			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 60 V			1	µA
		V_{GS} = 0 V, V_{DS} = 60 V, T_C = 125 °C			10	µA
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = ±16 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	1		2.8	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 1.5 A		0.07	0.10	Ω
		V_{GS} = 5 V, I_D = 1.5 A		0.085	0.12	

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0 V	-	340		pF
C_{oss}	Output capacitance		-	63		pF
C_{rss}	Reverse transfer capacitance		-	30		pF
Q_g	Total gate charge	V_{DD} = 48 V, I_D = 3 A	-	7	9	nC
Q_{gs}	Gate-source charge	R_G = 4.7 Ω, V_{GS} = 5 V	-	1.5		nC
Q_{gd}	Gate-drain charge	(see Figure 14. Test circuit for gate charge behavior)	-	2.8		nC

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 30 V, I_D = 1.5 A,	-	9	-	ns
t_r	Rise time	R_G = 4.7 Ω, V_{GS} = 5 V	-	25	-	ns
$t_{d(off)}$	Turn-off delay time	(see Figure 13. Test circuit for resistive load switching times and	-	20	-	ns
t_f	Fall time	Figure 18. Switching time waveform)	-	10	-	ns

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		4	A
I_{SDM}(1)	Source-drain current (pulsed)		-		16	A
V_{SD}(2)	Forward on voltage	I_{SD} = 4 A, V_{GS} = 0 V	-		1.5	V
t_{rr}	Reverse recovery time	I_{SD} = 4 A, di/dt = 100 A/µs,	-	50		ns
Q_{rr}	Reverse recovery charge	V_{DD} = 25 V, T_J = 150 °C	-	88		nC
I_{RRM}	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	3.5		A

1. *Pulse width limited by safe operating area.*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

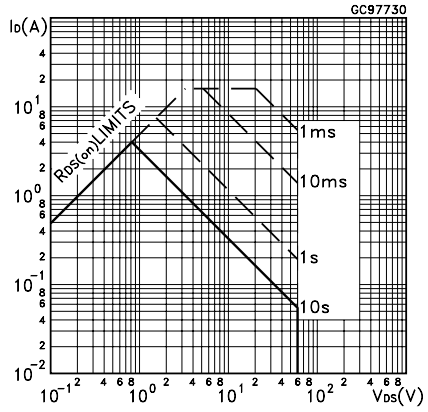


Figure 2. Thermal impedance

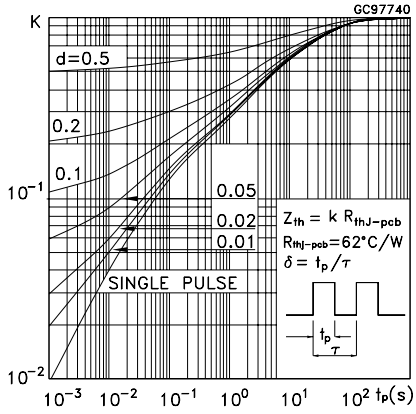


Figure 3. Output characteristics

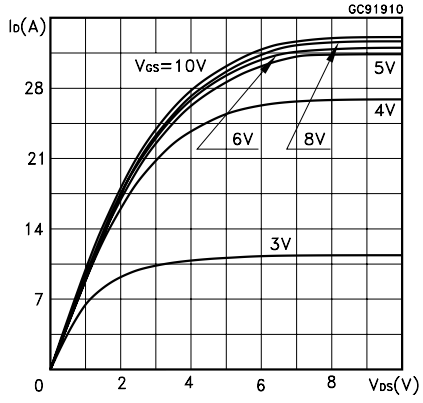


Figure 4. Transfer characteristics

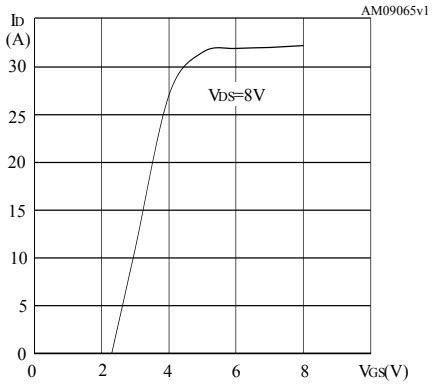


Figure 5. Static drain-source on resistance

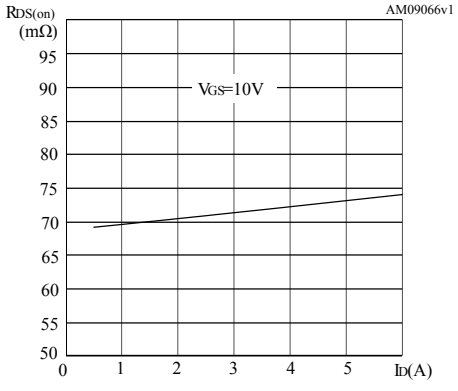


Figure 6. Gate charge vs. gate-source voltage

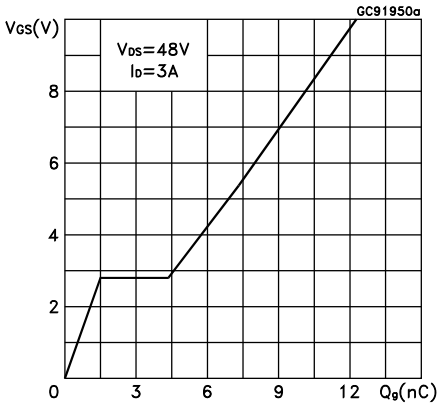


Figure 7. Capacitance variations

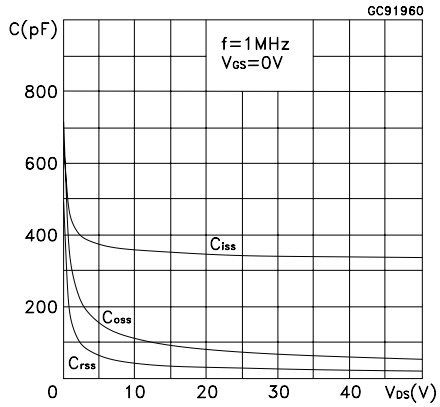


Figure 8. Normalized gate threshold voltage vs temperature

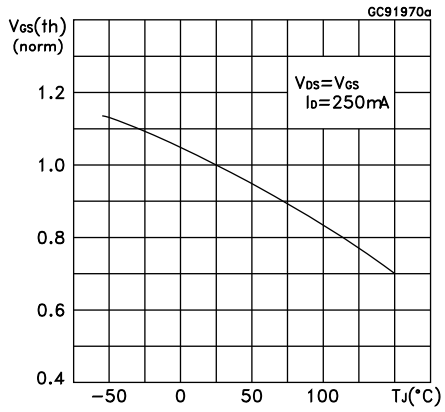


Figure 9. Normalized on-resistance vs temperature

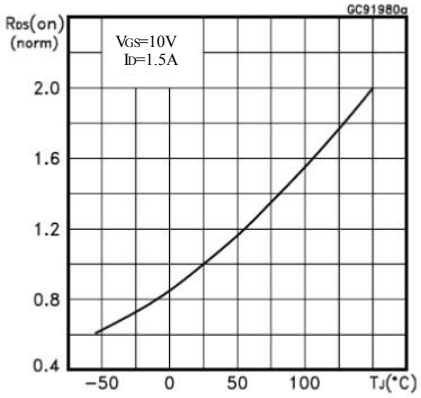


Figure 10. Source-drain diode forward characteristics

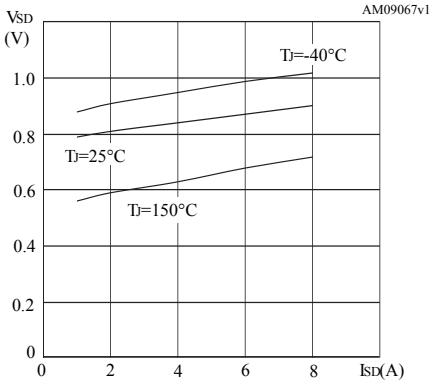
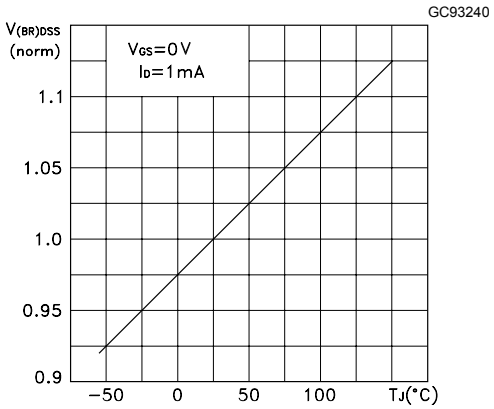


Figure 11. Normalized breakdown voltage vs temperature



3 Test circuits

Figure 12. Test circuit for resistive load switching times

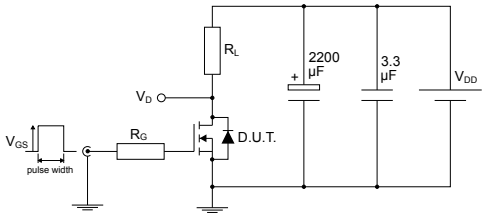


Figure 13. Test circuit for gate charge behavior

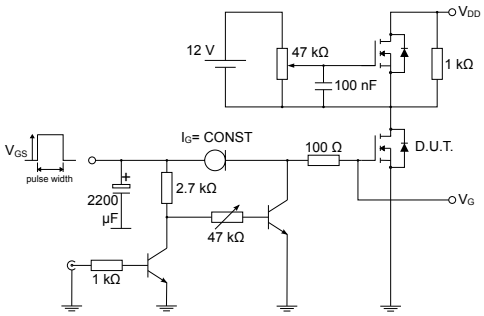


Figure 14. Test circuit for inductive load switching and diode recovery times

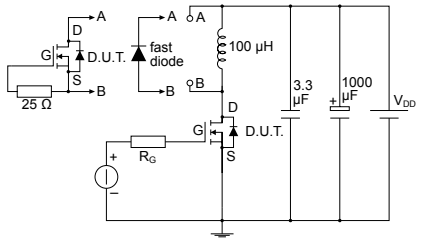


Figure 15. Unclamped inductive load test circuit

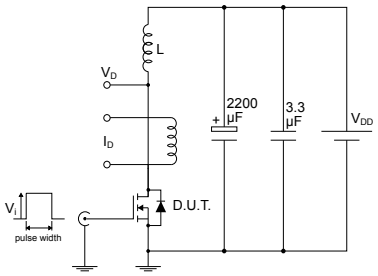


Figure 16. Unclamped inductive waveform

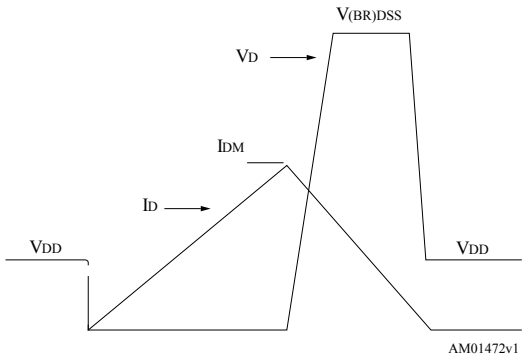
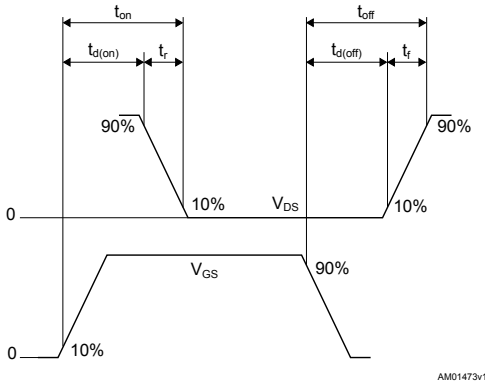


Figure 17. Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 SOT-223 package information

Figure 18. SOT-223 package outline

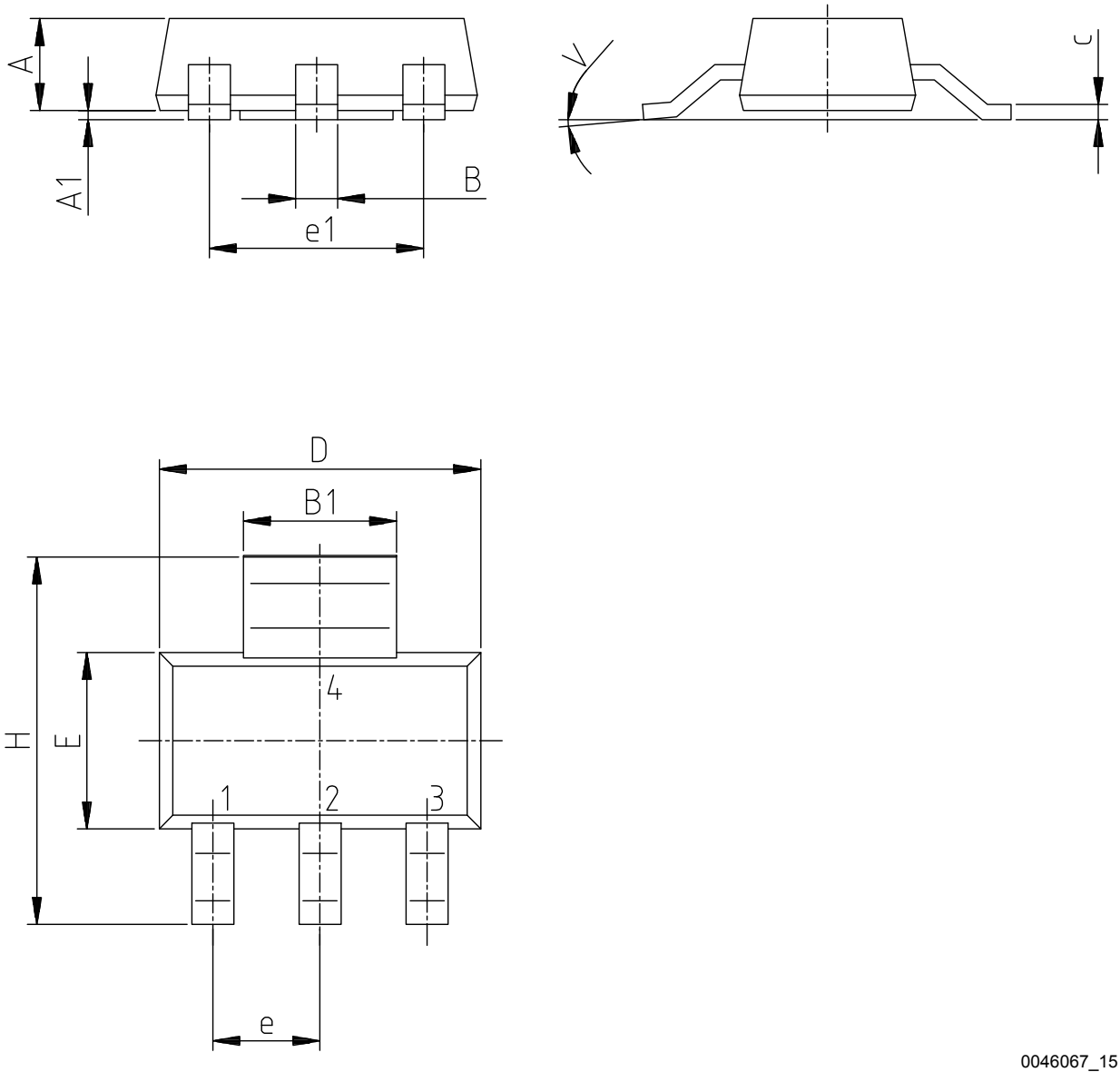
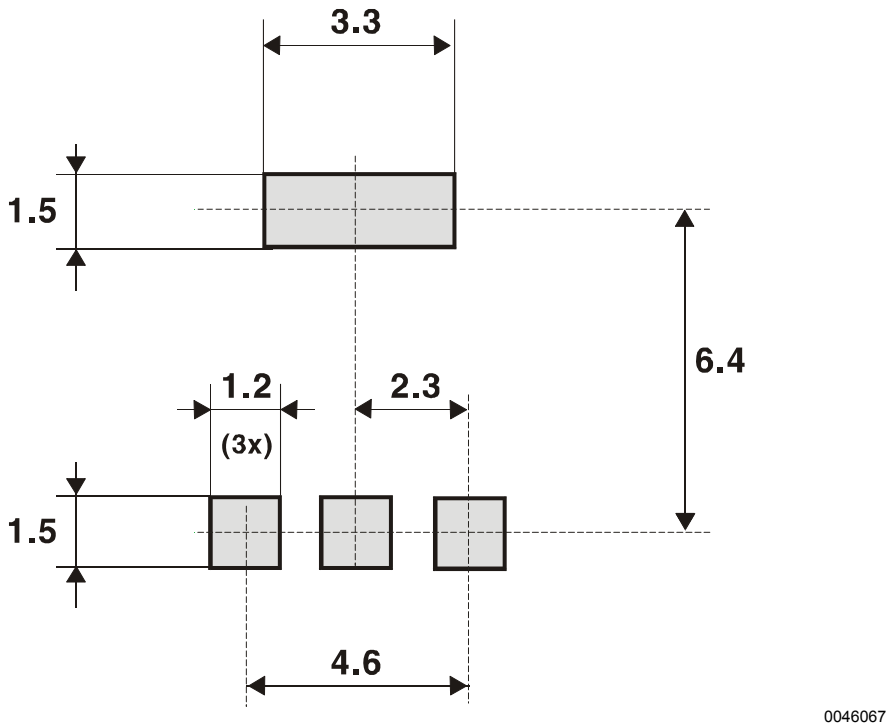


Table 7. **SOT-223 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A			1.8
B	0.6	0.7	0.85
B1	2.9	3	3.15
c	0.24	0.26	0.35
D	6.3	6.5	6.7
e		2.3	
e1		4.6	
E	3.3	3.5	3.7
H	6.7	7	7.3
V			10 deg
A1	0.02		0.1

Figure 19. **SOT-223 recommended footprint (dimensions are in mm)**



4.2 SOT-223 packing information

Figure 20. **SOT-223 tape outline**

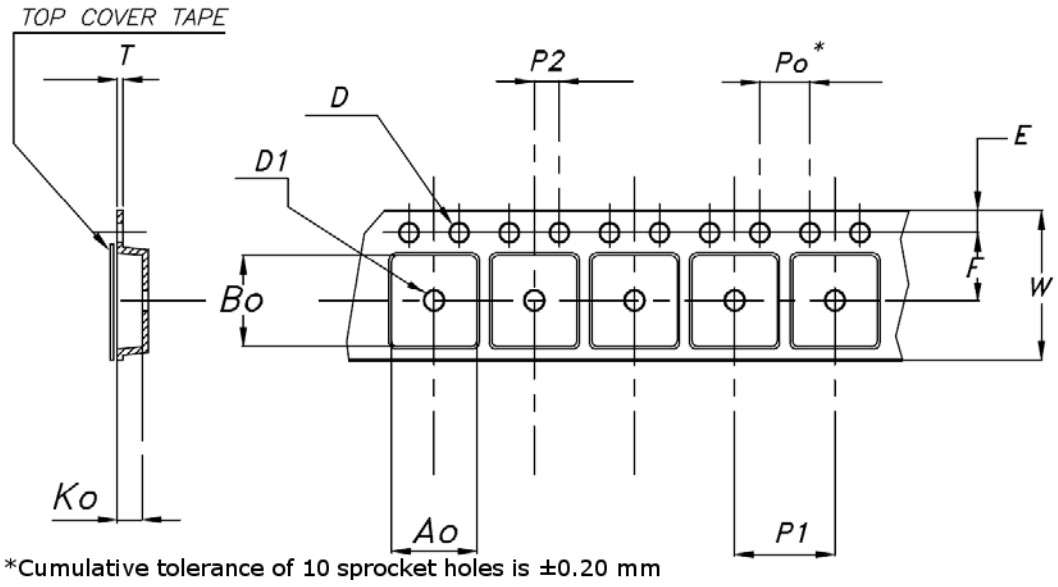


Figure 21. **SOT-223 reel outline**

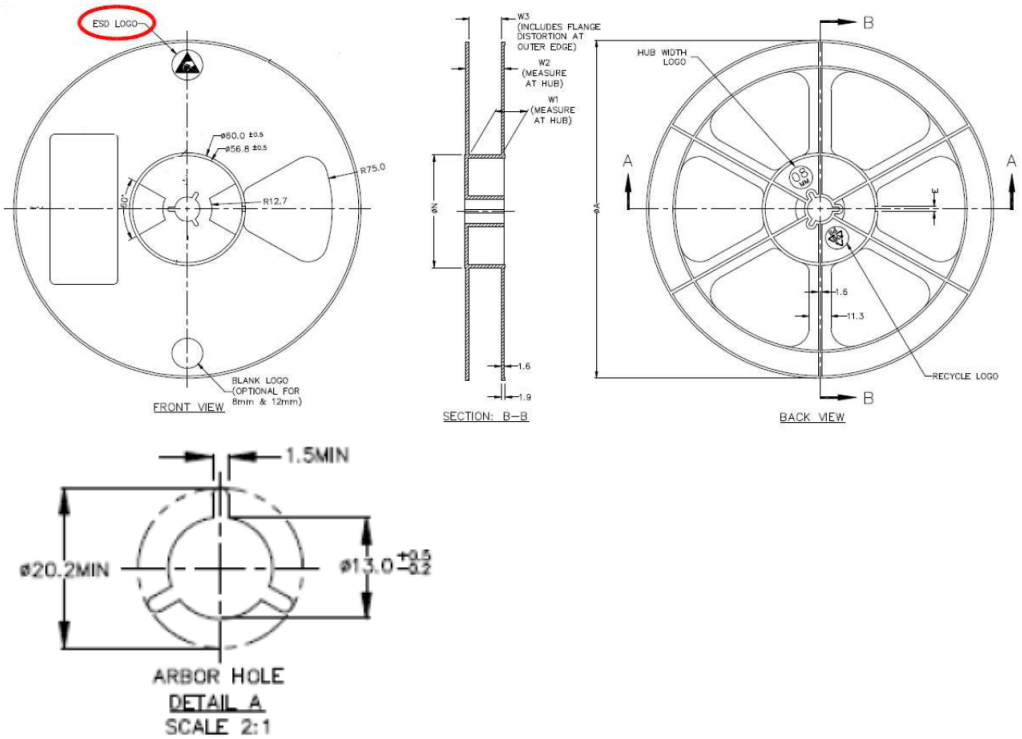


Table 8. **SOT-223 tape and reel mechanical data**

Tape				Tape		
Dim.	mm			Dim.	mm	
	Min.	Typ.	Max.		Min.	Max.
A0	6.75	6.85	6.95	A		180
B0	7.30	7.40	7.50	N	60	
K0	1.80	1.90	2.00	W1		12.4
F	5.40	5.50	5.60	W2		18.4
E	1.65	1.75	1.85	W3	11.9	15.4
W	11.7	12.0	12.3			
P2	1.90	2.00	2.10	Base quantity pcs		1000
P0	3.90	4.00	4.10	Bulk quantity pcs		1000
P1	7.90	8.00	8.10			
T	0.25	0.30	0.35			
DΦ	1.50	1.55	1.60			
D1Φ	1.50	1.60	1.70			

Revision history

Table 9. **Document revision history**

Date	Version	Changes
22-Apr-2008	1	Initial version.
29-Apr-2011	2	*Figure 5*, *Figure 7*, *Figure 11* and *Figure 12* have been updated.
05-May-2020	3	Updated Section 4.1 SOT-223 package information. Minor text changes.

Contents